









CEU13N65S

650V ▲ 0.27Ω ▲ 12.3A ▲ Si MOSFET

SILICON Si MOSFET ▲ SMD type

N-channel enhancement mode

UL94V-0 rated flame retardant epoxy

TO252 (DPAK) package ▲ MSL 3

Super high dense cell density for extremely low R_{DS(ON)}

High power and current handling capability

MAXIMUM RATINGS

Parameter (T _C = 25°C, unless otherwise noted)	Characteristics	
Drain-Source Voltage	V _{DS}	650V
Gate-Source Voltage	V _{GS}	±30V
Continuous Drain Current at T _C = 25°C	I _D	12.3A
Continuous Drain Current at T _C = 100°C	I _D	7.8A
Pulsed Drain Current Note 1	I _{DM}	49.2A
Maximum Power Dissipation at T _C = 25°C	P _D	125W
Power Dissipation Derating above 25°C	ΔP_D	1W/°C
Single Pulsed Avalanche Energy Note 5	E _{AS}	306mJ
Single Pulsed Avalanche Current Note 5	l _{AS}	3.5A
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +150°C

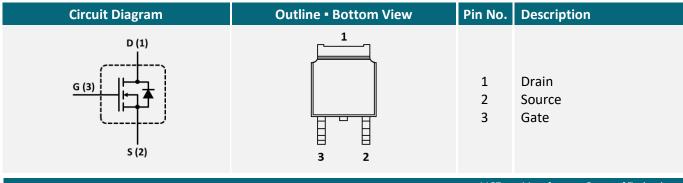
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R _{TH_JC}	1°C/W
Thermal Resistance, Junction-to-Ambient	R _{TH JA}	50°C/W

APPLICATIONS

EV Charging	Industrial Inverters	Motors & Drives	Power Factor Correction	Renewable Energy	SMPS	UPS
₹	0		PFC	*		

PIN DESCRIPTION



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ELECTRICAL CHARACTERISTICS ▲ T_C = 25°C, unless otherwise noted

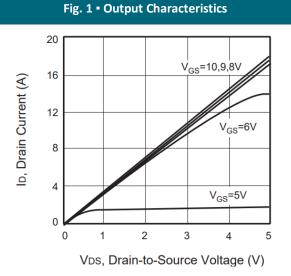
Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV_{DSS}	650			V
Zero Gate Voltage Drain Current	$V_{DS} = 650V, V_{GS} = 0V$	I _{DSS}			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	I _{GSSF}			100	nA
Gate Body Leakage Current, Reverse	V_{GS} = -30V, V_{DS} = 0V	I _{GSSR}			-100	nA
On Characteristics Note 3						
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	$V_{GS(th)}$	2.5		4.5	V
Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 5.5A$	R _{DS(ON)}		0.27	0.32	Ω
Gate Input Resistance	f = 1MHz, Open Drain	R_{G}		8		Ω
Dynamic Characteristics Note 4						
Input Capacitance	$V_{DS} = 150V$, $V_{GS} = 0V$, $f = 1MHz$	C _{ISS}		910		pF
Output Capacitance	$V_{DS} = 150V$, $V_{GS} = 0V$, $f = 1MHz$	Coss		60		pF
Reverse Transfer Capacitance	$V_{DS} = 150V$, $V_{GS} = 0V$, $f = 1MHz$	C _{RSS}		15		pF
Switching Characteristics Note 4						
Turn-On Delay Time	V_{DD} = 400V, V_{GS} = 10V, I_D = 6A, $R_{G(ext)}$ = 10 Ω	$t_{\text{D(ON)}}$		30		ns
Turn-On Rise Time	V_{DD} = 400V, V_{GS} = 10V, I_D = 6A, $R_{G(ext)}$ = 10 Ω	t_{R}		13		ns
Turn-Off Delay Time	$V_{DD} = 400V$, $V_{GS} = 10V$, $I_{D} = 6A$, $R_{G(ext)} = 10\Omega$	t _{D(OFF)}		65		ns
Turn-Off Fall Time	$V_{DD} = 400V, V_{GS} = 10V, I_{D} = 6A,$ $R_{G(ext)} = 10\Omega$	t _F		11		ns
Total Gate Charge	$V_{DS} = 400V$, $V_{GS} = 10V$, $I_D = 1A$	Q_{G}		25		nC
Gate Source Charge	$V_{DS} = 400V$, $V_{GS} = 10V$, $I_D = 1A$	Q_{GS}		4		nC
Gate Drain Charge	$V_{DS} = 400V$, $V_{GS} = 10V$, $I_D = 1A$	Q_{GD}		10		nC
Drain-Source Diode Characteristics a	nd Maximum Ratings					
Drain-Source Diode Forward Current		Is			12.3	Α
Drain-Source Diode Forward Voltage Note 3	V _{GS} = 0V, I _S = 6A	V_{SD}			1.2	V
Reverse Recovery Time	$I_D = 6A$, di/dt = 100A/ μ s	t_{RR}		240		ns
Reverse Recovery Charge	$I_D = 6A$, di/dt = 100A/ μ s	Q_{RR}		2.35		μC
Peak Reverse Recovery Current	$I_D = 6A$, di/dt = 100A/ μ s	I _{RR}		16.8		Α

Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2: Surface Mounted on FR4 Board, t < 10 sec.
- 3: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4: Guaranteed by design, not subject to production testing.
- 5: L = 50mH, $I_{AS} = 3.5A$, $V_{DD} = 50V$, $R_G = 25Ω$, Starting $T_J = 25$ °C

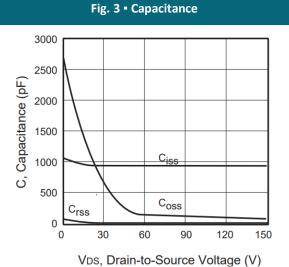


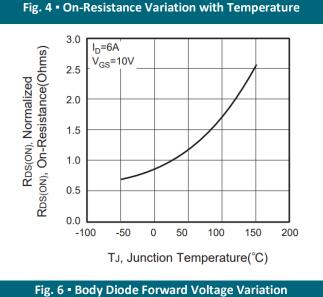
REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

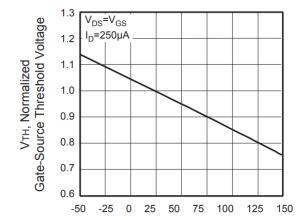


Vgs, Gate-to-Source Voltage (V)

Fig. 2 • Transfer Characteristics

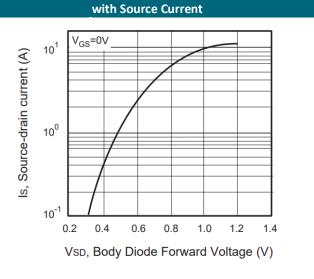






T_J, Junction Temperature(°C)

Fig. 5 • Gate Threshold Variation with Temperature



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REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

Fig. 7 • Gate Charge

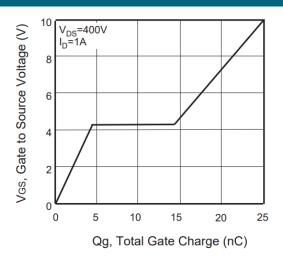


Fig. 8 • Maximum Safe Operating Area

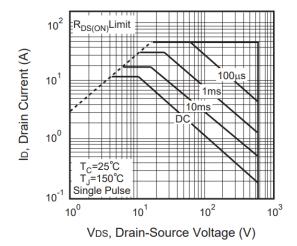
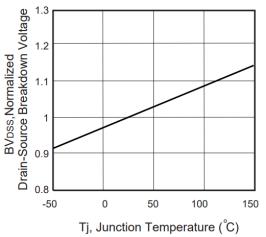


Fig. 9 • Breakdown Voltage Variation vs. Temperature





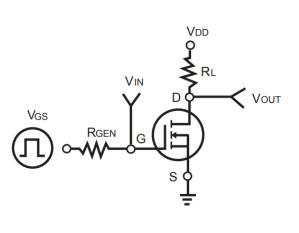
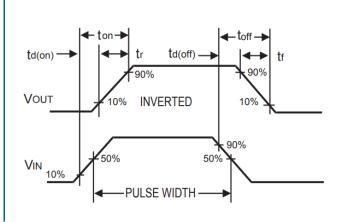


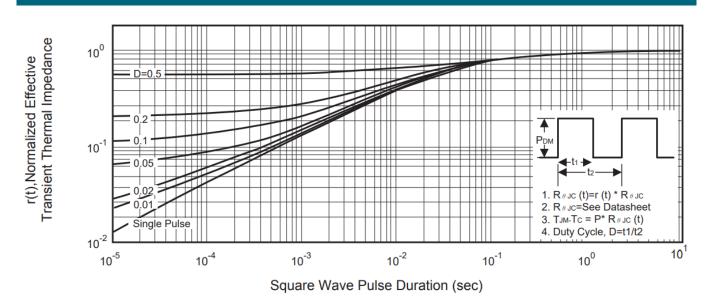
Fig. 11 • Switching Waveforms



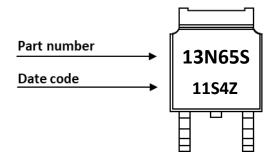


REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

Fig. 12 • Normalized Thermal Transient Impedance Curve

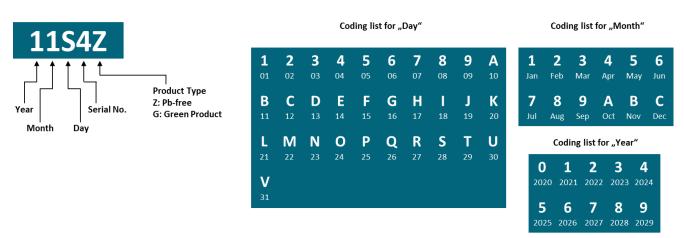


PART MARKING



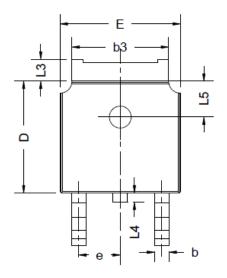
DATE CODE

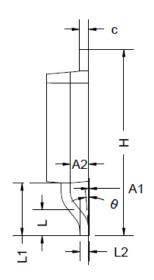
Example: 11S4Z

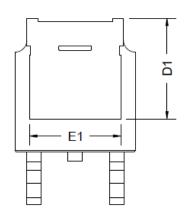


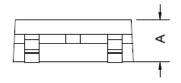


PACKAGE OUTLINE









Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)	
Α	2.20	2.30	2.38	
A1	0.00	-	0.20	
A2	A2 0.90 1.07		1.17	
b	0.68	0.78	0.90	
b3	5.23	5.33	5.46	
С	0.43	0.53	0.61	
D	5.98 6.10		6.22	
D1		5.30 REF		
Е	6.40	6.60	6.73	
E1	4.63	-	-	

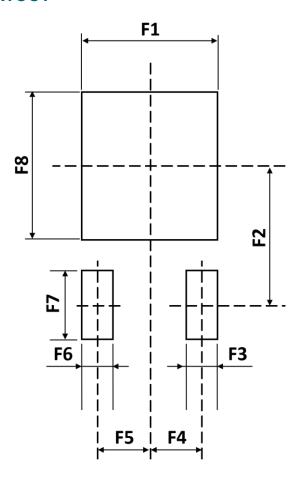
Sym	Millimeters (Min.)	Millimeters (Max.)					
e		2.286 BSC					
Н	9.40	10.10	10.50				
L	1.38	1.50	1.75				
L1	2.90 REF						
L2		0.51 BSC					
L3	0.88	-	1.28				
L4	0.50		1.00				
L5	1.65	1.80	1.95				
θ	0°	-	8°				

ORDERING INFORMATION

Part Number	Package	Packing	Reel Qty.	Inner Box Qty.	Outer Box Qty.
CEU13N65S	TO252 (DPAK)	Reel	2,500pcs	5,000pcs	40,000pcs



RECOMMENDED PAD LAYOUT



Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)	
F1	-	6.00	-	
F2	-	6.25	-	
F3	-	1.40	-	
F4	-	2.29	-	

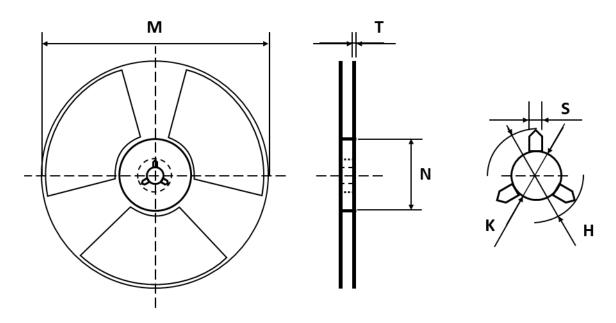
Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
F5	-	2.29	-
F6	-	1.40	-
F7	-	3.00	-
F8	-	6.50	-

Notes:

- 1. The suggested land pattern dimensions have been provided for reference only.
- 2. For further information, please reference document IPC-7351A.

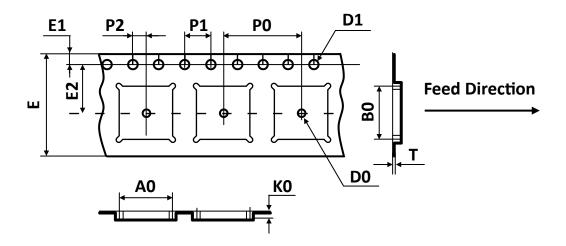


REEL DIMENSIONS ▲ All dimensions in mm



Tape Size	Reel Size	M	N	T	н	К	S
		Ø330.00	Ø100.00	2.10	22.00	13.00	2.00
16mm	Ø330	±2.00	±0.50	±0.20	+0 50	+0.50	+0.50
		±2.00	±0.50	±0.20	±0.50	-0.20	-0.20

TAPE DIMENSIONS ▲ All dimensions in mm

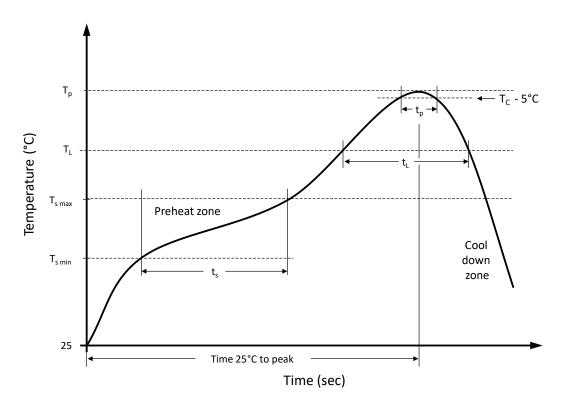


Package	A0	В0	КО	D0	D1	E	E1	E2	P0	P1	P2	Т
TO252	6.90	10.50	2.70	1.50	1.50	16.00	1.75	7.50	8.00	4.00	2.00	0.30
(DPAK)	±0.10	±0.10	±0.10	MIN	±0.10	+0.30	±0.10	±0.10	±0.10	±0.10	±0.10	±0.05

Note: All dimensions meet EIA-481-D requirements.



RECOMMENDED REFLOW SOLDERING PROFILE



Recommended reflow soldering conditions ▲ **Refer to JEDEC J-STD-020E**

Profile Features		Sn-Pb Eutetic Assembly	Pb-Free Assembly
Preheat temperature min.	$T_{s min}$	100 °C	150 °C
Preheat temperature max.	T _{s max}	150 °C	200 °C
Preheat time t _s from T _{s min} to T _{s max}	ts	120 seconds	120 seconds
Ramp-up rate (T₁ to Tp)		max. 3 °C/second	max. 3 °C/second
Liquidous temperature	T_L	183 °C	217 °C
Time t _L maintained above T _L	t _L	150 seconds max.	150 seconds max.
Peak package body temperature	Tp	235°C	260°C
Timeframe of within 5°C below and up to max actual peak body temperature	t _p	20 seconds max.	30 seconds max.
Ramp-down rate (T _L to T _p)		max. 6 °C/second	max. 6 °C/second
Time 25°C to peak temperature		max. 6 minutes	max. 8 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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